

**DMSMS NOTICE**

DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES

1. TITLE MICROCIRCUIT, DIGITAL, ADVANCED CMOS, RADIATION HARDENED, SYNCHRONOUS 4-BIT BINARY UP/DOWN COUNTER, TLL COMPATIBLE INPUTS, MONOLITHIC SILICON		2. DOCUMENT NUMBER SPO-2012-D-0010	
		3. DATE (Year, Month, Date) 2012 May 02	
4. MANUFACTURER NAME AND ADDRESS CAES 4350 CENTENNIAL BOULEVARD COLORADO SPRINGS, COLORADO 80907-3486		5. MANUFACTURER POINT OF CONTACT (NAME) MR. TIM MEADE	
		6. MANUFACTURER POINT OF CONTACT TELEPHONE (719) 594-8048	
		7. MANUFACTURER POINT OF CONTACT EMAIL tim.l.meade@cobhamaes.com	
8. CAGE CODE 65342	9. MANUFACTURER FINAL ORDER DATE SEE COMMENTS BELOW	10. PRODUCT IDENTIFICATION CODE LA193A	11. BASE PART UT54ACTS193
12. BLANK		13. SMD NUMBER 96567	14. DEVICE TYPE DESIGNATOR 01
		15. RHA LEVELS NON, R, F, G, AND H	16. QML LEVEL Q AND V
		17. NON QML LEVEL N/A	18. BLANK

19. COMMENTS

CAES IS ISSUING THIS DIMINISHING MANUFACTURING SOURCES AND MATERIAL SHORTAGES NOTICE AND PRODUCT CHANGE NOTIFICATION TO ANNOUNCE THE FOUNDRY MIGRATION OF DEVICE TYPE 01 FROM 1.2UM RADIATION-HARDENED CMOS TO ON-SEMICONDUCTOR'S 0.6UM C5U COMMERCIAL RADIATION-HARDENED CMOS PROCESS. BECAUSE THE MIGRATED DEVICE IS FORM, FIT, AND FUNCTIONAL TO THE LEGACY DEVICE, IT WILL CONTINUE TO SHIP AS DEVICE TYPE 01.

AS PART OF THIS PROCESS MIGRATION, THE RADIATION HARDNESS ASSURANCE LEVEL "H" AND CASE OUTLINE "E" WILL NO LONGER BE AVAILABLE FROM AN APPROVED SOURCE OF SUPPLY. CAES IS NO LONGER ACCEPTING PURCHASE ORDERS FOR PRODUCT WITH THE RHA LEVEL "H" OR CASE OUTLINE "E". ADDITIONALLY, DIE SALES AGAINST DIE DETAIL "A" ARE NO LONGER AVAILABLE. FUTURE DIE SALES MAY BE ISSUED AGAINST DIE DETAIL "B" OF THE AFFECTED SMD. NOTE: THE NEW DIE SUPPLIED AGAINST DIE DETAIL "B" REQUIRE A SUBSTRATE BIAS TO VSS.

THE MIGRATED DEVICE OFFERING WILL BE AVAILABLE WITH THE FOLLOWING OPTIONS:

SMD #: 5962-96527 DEVICE TYPE: 01  
AVAILABLE RHA DESIGNATORS: R (100Krad (Si)), F (300Krad (Si)), G (500Krad (Si))  
DEVICE CLASS: Q, V  
CASE OUTLINE DESIGNATOR: X (14 LEAD FLAT PACK) OR DIE CODE: 9  
LEAD FINISH: A, C, X OR DIE DETAIL: B

SHIPMENTS OF THE MIGRATED DEVICE ARE EXPECTED TO BEGIN IN MAY 2012.

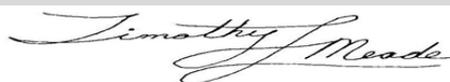
Obsolete SMD PINs	Vendor Similar PINs
5962 H 96567 01 V E A	UT54ACTS193- PVAH
5962 H 96567 01 V X A	UT54ACTS193- UVAH
5962 H 96567 01 V E C	UT54ACTS193- PVCH
5962 H 96567 01 V X C	UT54ACTS193- UVCH
5962 H 96567 01 Q E A	UT54ACTS193- PQAH
5962 H 96567 01 Q X A	UT54ACTS193- UQAH
5962 H 96567 01 Q E C	UT54ACTS193- PQCH
5962 H 96567 01 Q X C	UT54ACTS193- UQCH
5962 H 96567 01 V 9 A	UT54ACTS193- VDIE
5962 H 96567 01 Q 9 A	UT54ACTS193- QDIE

Replace SMD PINs	Vendor Similar PINs
5962 G 96567 01 V X A	UT54ACTS193- UVAG
5962 G 96567 01 V X C	UT54ACTS193- UVCG
5962 G 96567 01 Q X A	UT54ACTS193- UQAG
5962 G 96567 01 Q X C	UT54ACTS193- UQCG
5962 G 96567 01 V 9 B	UT54ACTS193- VDIE
5962 G 96567 01 Q 9 B	UT54ACTS193- QDIE

20. ADEPT REPRESENTATIVE

Timothy L. Meade

21. SIGNATURE



22. DATE

2012, May, 07